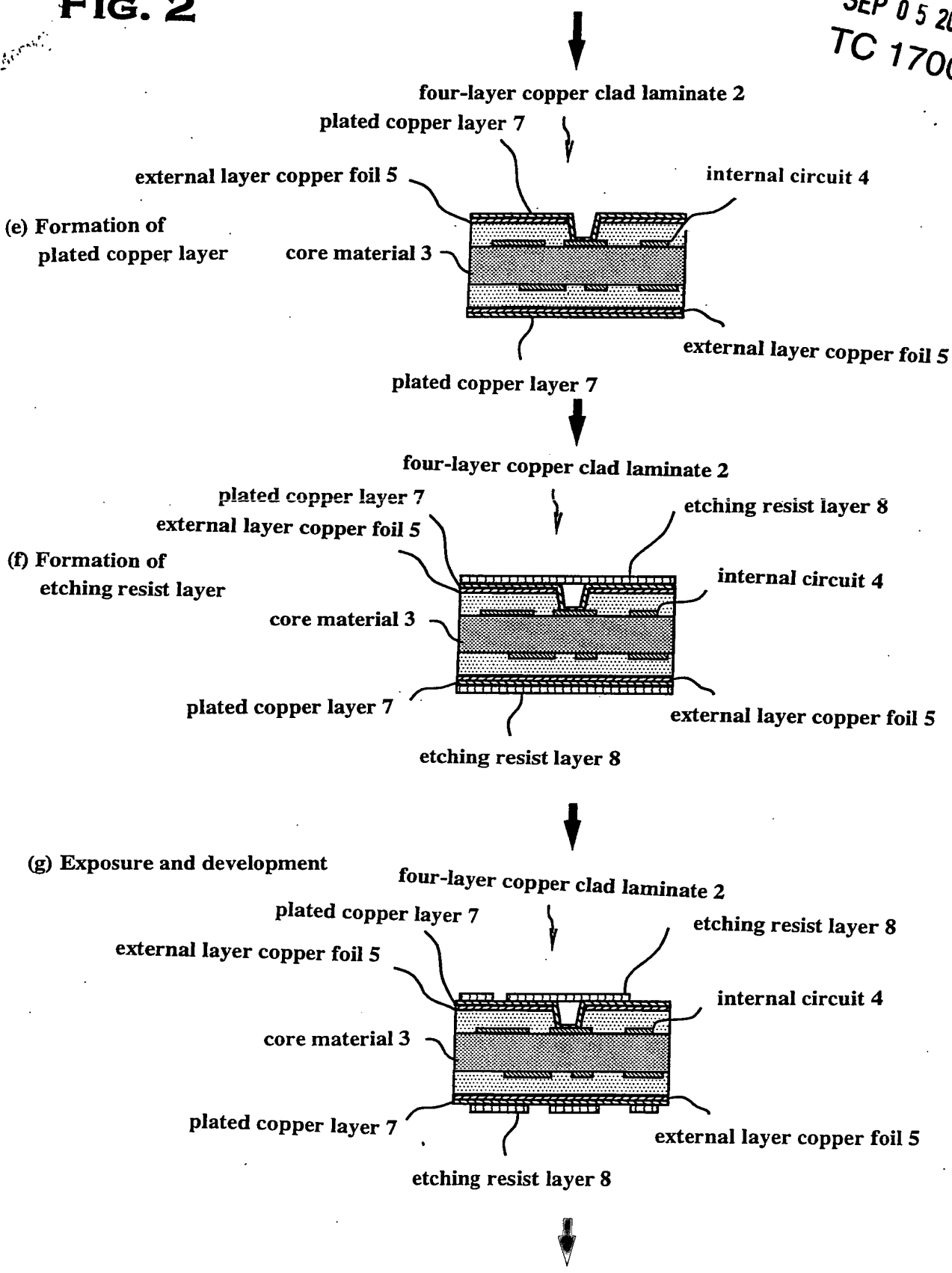


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FIG. 2



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FIG. 2

(e) Formation of
plated copper layer

four-layer copper clad laminate 2
plated copper layer 7
external layer copper foil 5
internal circuit 4
etching resist layer 8

core material 3

external layer copper foil 5

plated copper layer 7

(f) Formation of
etching resist layer

four-layer copper clad laminate 2
plated copper layer 7
external layer copper foil 5
etching resist layer 8

core material 3

internal circuit 4

plated copper layer 7

external layer copper foil 5

etching resist layer 8

(g) Exposure and development

four-layer copper clad laminate 2
plated copper layer 7
external layer copper foil 5
etching resist layer 8

core material 3

internal circuit 4

plated copper layer 7

external layer copper foil 5

etching resist layer 8